Product Bulletin

Document #:PB25168X
Issue Date:01 Apr 2023

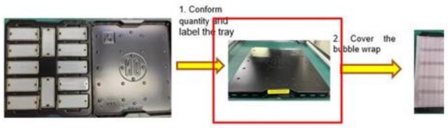
Title of Change:	New Q2 Blister Tray and Outbox Suppliers Qualification
Effective date:	01 Apr 2023
Contact information:	Contact your local onsemi Sales Office or *Way-Shan.Yong@onsemi.com*
Type of notification:	This Product Bulletin is for notification purposes only. onsemi will proceed with implementation of this change upon publication of this Product Bulletin.
Change Category:	Packing materials change
Change Sub-Category(s):	Shipping/Packaging/Marking, Material Change

Sites Affected:

onsemi Sites	**External Foundry/Subcon Sites**
None	None

Description and Purpose:

This PB announces the change of packing method for PIM Q2 modules. The change is planned at onsemi Shenzhen, China.

	Before Change Description	**After Change Description (Fully Pallet)**
Packing method for PIM Q2 modules	Q2 blister tray from current supplier	Q2 blister tray from current and new supplier
	TIM blister tray no stacking	TIM blister tray **stacking**
	Outbox from MYD + Old Logo	Outbox from MYD/**new supplier + New Logo**
	• Current: single structure (12 units/tray)  	• Proposed: stacking structure (36 units/ tray) 

List of Affected Standard Parts:

Note*: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the* ***PCN Customized Portal****.*

NXH200T120H3Q2F2STNG		